

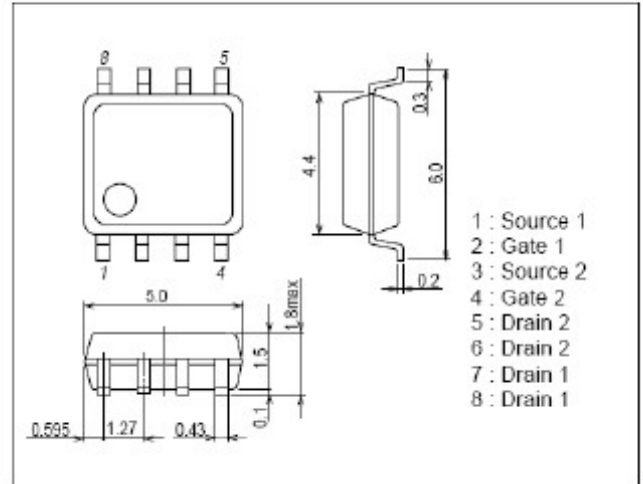
Features

- Low On resistance
- 4.5V/-4.5V drive
- RoHS compliant



Package Dimensions

unit : mm
SOP-8



Absolute Maximum Ratings $T_A = 25^\circ\text{C}$

Parameter	Symbol	Conditions	Ratings		Unit
			N-Ch	P-Ch	
Drain-to-Source Voltage	V_{DSS}	Drain-Source Voltage	60	-60	V
Gate-to-Source Voltage	V_{GSS}	Gate-Source Voltage	± 25	± 25	V
Drain Current (DC)	I_D	Continuous Drain Current	5	-3.5	A
Drain Current (Pulse)	I_{DP}	$PW \leq 10\mu\text{S}$, duty cycle $\leq 1\%$	20	-14	A
Allowable Power Dissipation	P_D	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$) 1unit	1.3		W
Total Dissipation	P_T	Mounted on a ceramic board ($1000\text{mm}^2 \times 0.8\text{mm}$)	1.7		W
Channel Temperature	T_{ch}	Maximum Junction Temperature	150		$^\circ\text{C}$
Storage Temperature	T_{stg}	Storage Temperature Range	-55~+150		$^\circ\text{C}$

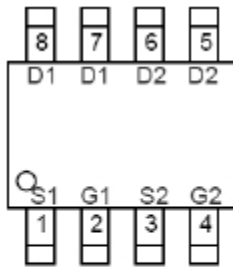


Electrical Characteristics $T_A = 25^\circ\text{C}$							
Parameter	Symbol	Conditions		Ratings			Unit
				Min.	Typ.	Max.	
Drain-to-Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	N-Ch	60	--	--	V
		$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	P-Ch	-60	--	--	
Zero-Gate Voltage Drain Current	I_{DSS}	$V_{DS} = 48\text{V}, V_{GS} = 0\text{V}$	N-Ch	--	--	1	μA
		$V_{DS} = -48\text{V}, V_{GS} = 0\text{V}$	P-Ch	--	--	-1	
Gate-to-Source Leakage Current	I_{GSS}	$V_{GS} = +25\text{V}, V_{DS} = 0\text{V}$	N-Ch	--	--	± 100	nA
		$V_{GS} = +25\text{V}, V_{DS} = 0\text{V}$	P-Ch	--	--	± 100	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$	N-Ch	1	2	2.5	V
		$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	P-Ch	-1	-2	-2.5	
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	$I_D = 5\text{A}, V_{GS} = 10\text{V}$	N-Ch	--	38	52	$\text{m}\Omega$
		$I_D = -3.5\text{A}, V_{GS} = -10\text{V}$	P-Ch	--	80	100	

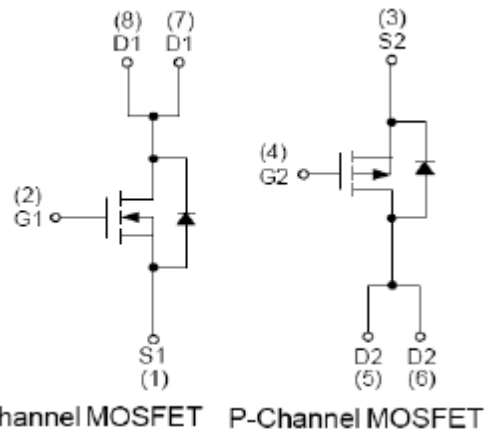


Electrical Characteristics $T_A = 25^\circ\text{C}$ (Continued)							
Parameter	Symbol	Conditions		Ratings			Unit
				Min.	Typ.	Max.	
Static Drain-to-Source On-State Resistance	$R_{DS(ON)}$	$I_D = 4\text{A}, V_{GS} = 4.5\text{V}$	N-Ch	--	55	75	m Ω
		$I_D = -3.1\text{A}, V_{GS} = -4.5\text{V}$	P-Ch	--	100	135	
Input Capacitance	C_{ISS}	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	N-Ch	--	915	--	pF
		$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	P-Ch	--	1050	--	
Output Capacitance	C_{OSS}	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	N-Ch	--	70	--	pF
		$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	P-Ch	--	70	--	
Reverse Transfer Capacitance	C_{RSS}	$V_{DS} = 30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	N-Ch	--	45	--	pF
		$V_{DS} = -30\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$	P-Ch	--	50	--	
Turn-on Delay Time	$t_{d(on)}$	<p>N-Channel</p> <p>$V_{GEN} = 10\text{V}, V_{DS} = 30\text{V},$ $R_L = 30\Omega, I_D = 1\text{A}, R_{GEN} = 6\Omega$</p> <p>P-Channel</p> <p>$V_{GEN} = -10\text{V}, V_{DS} = -30\text{V},$ $R_L = 30\Omega, I_D = -1\text{A}, R_{GEN} = 6\Omega$</p>	N-Ch	--	9	17	nS
			P-Ch	--	7	14	
Rise Time	t_r		N-Ch	--	6	12	nS
			P-Ch	--	8	15	
Turn-off Delay Time	$t_{d(off)}$	N-Ch	--	25	46	nS	
		P-Ch	--	47	86		
Fall Time	t_f	N-Ch	--	5	10	nS	
		P-Ch	--	17	32		
Total Gate Charge	Q_g	<p>N-Channel</p> <p>$V_{DS} = 30\text{V}, V_{GS} = 10\text{V}, I_D = 5\text{A}$</p> <p>P-Channel</p> <p>$V_{DS} = -30\text{V}, V_{GS} = -10\text{V},$</p>	N-Ch	--	19	27	nC
			P-Ch	--	22	31	
Gate-to-Source Charge	Q_{gs}		N-Ch	--	4.4	--	nC
			P-Ch	--	2.8	--	
Gate-to-Drain "Miller" Charge	Q_{gd}	N-Ch	--	4.4	--	nC	
		P-Ch	--	5	--		
Diode Forward Voltage	V_{SD}	$I_S = 2.5\text{A}, V_{GS} = 0\text{V}$	N-Ch	--	0.8	1.1	V
		$I_S = -2.5\text{A}, V_{GS} = 0\text{V}$	P-Ch	--	-0.8	-1.1	

Pin Description



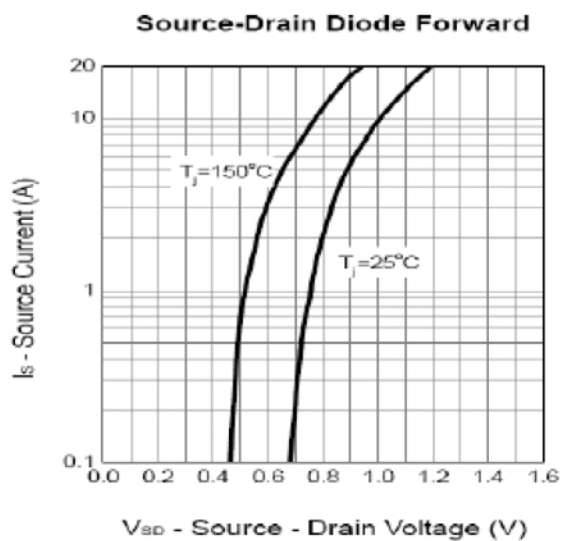
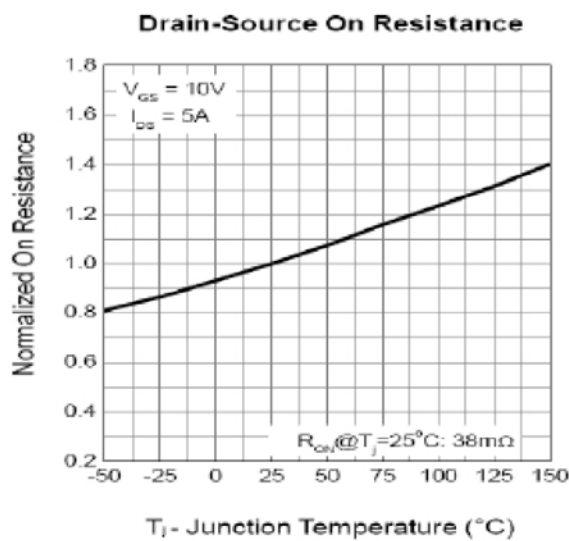
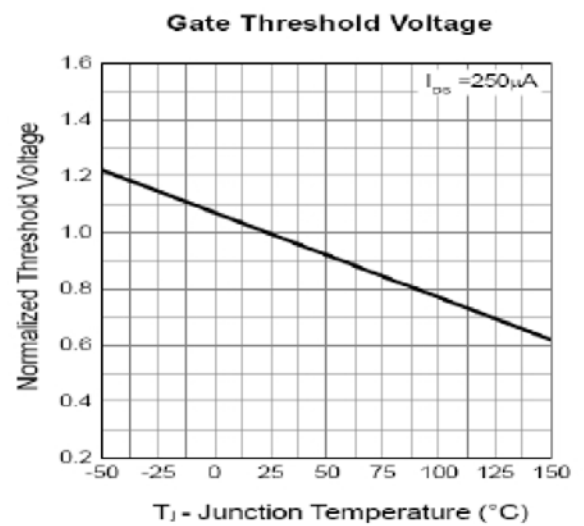
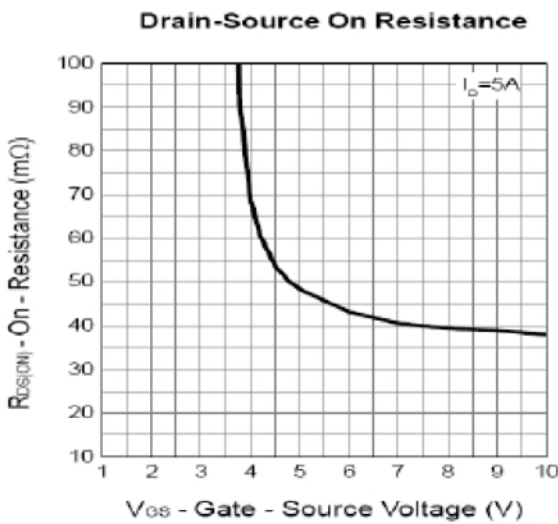
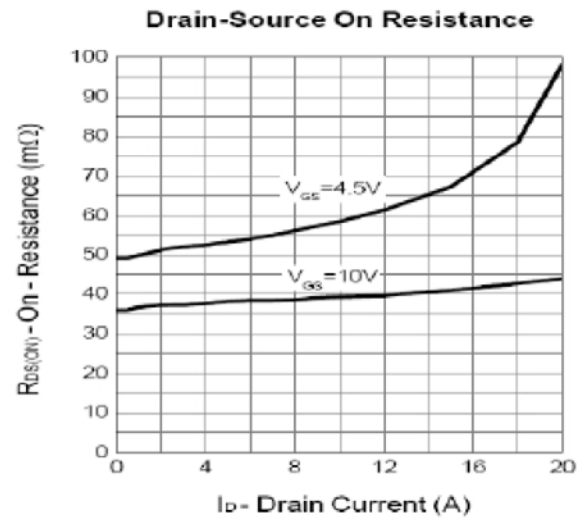
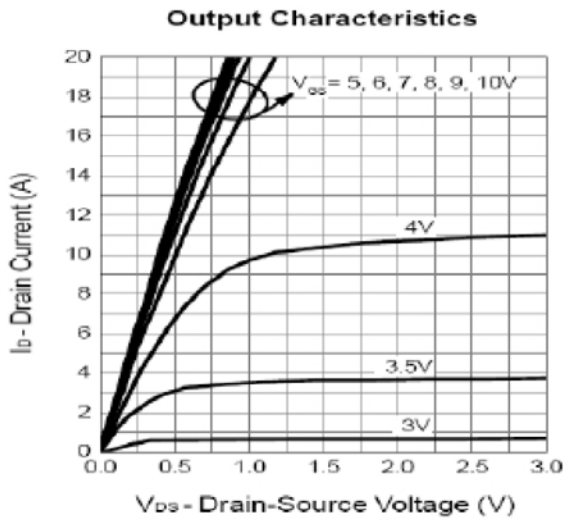
TOP VIEW
SOP-8



N-Channel MOSFET P-Channel MOSFET

Typical Characteristics TA=25°C

N-Channel

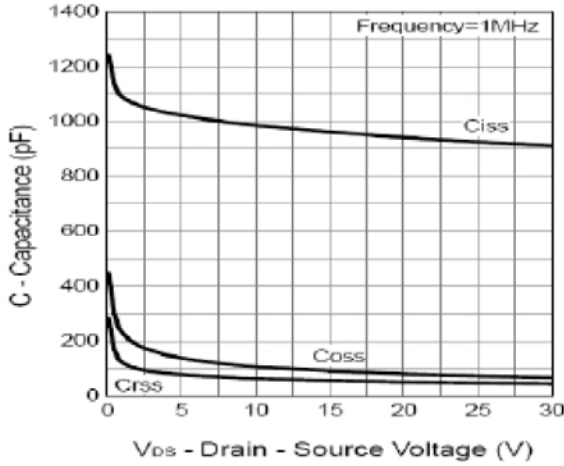




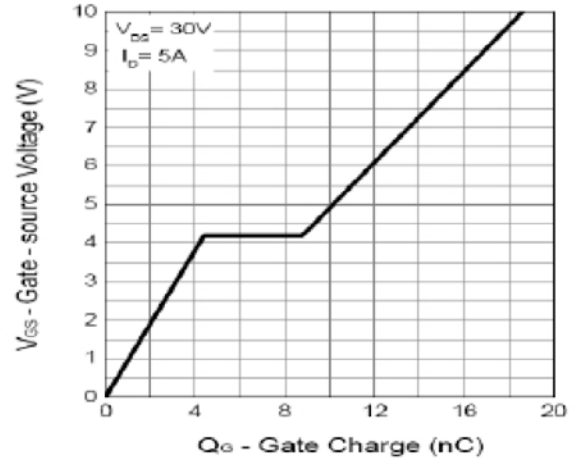
Typical Characteristics TA=25°C

N-Channel

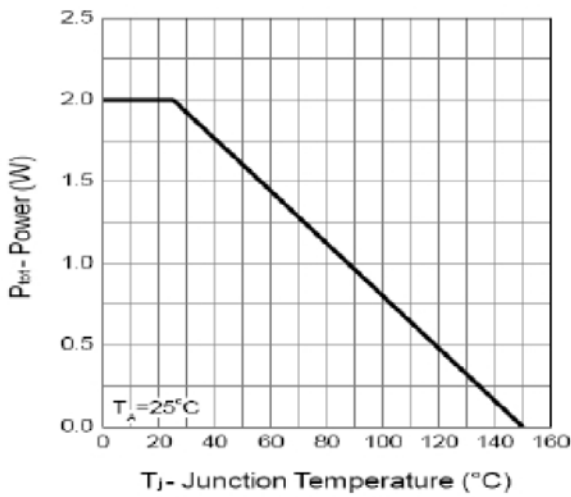
Capacitance



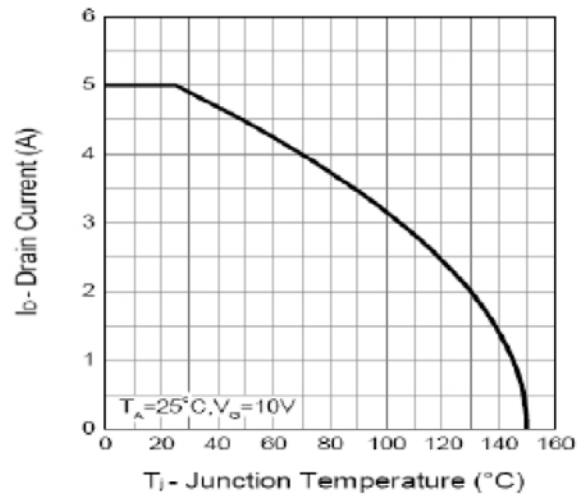
Gate Charge



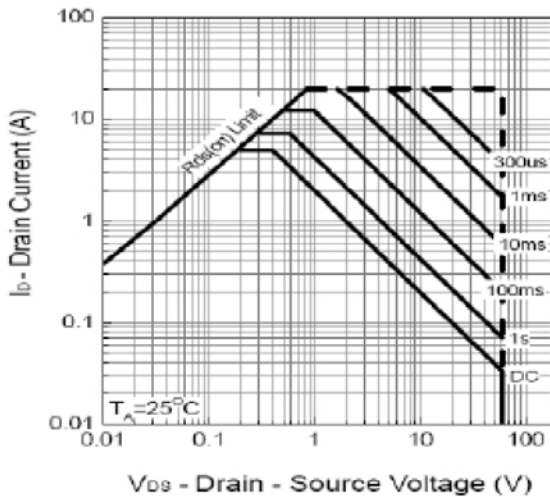
Power Dissipation



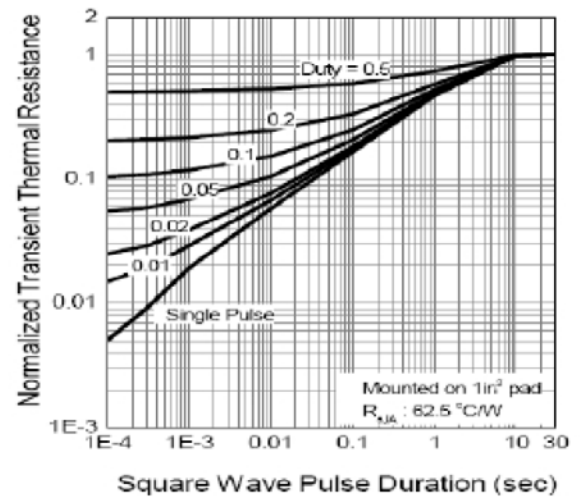
Drain Current



Safe Operation Area

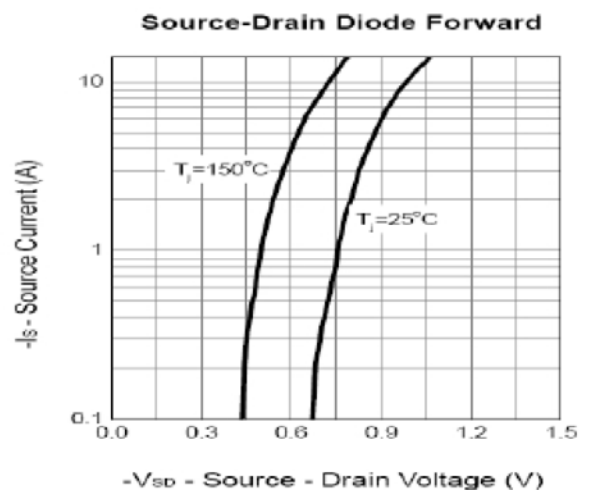
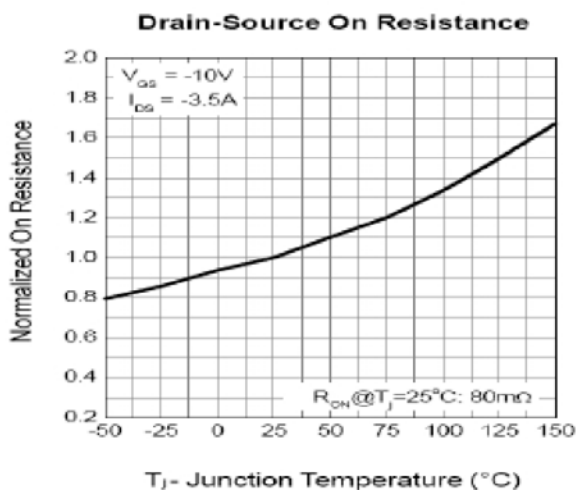
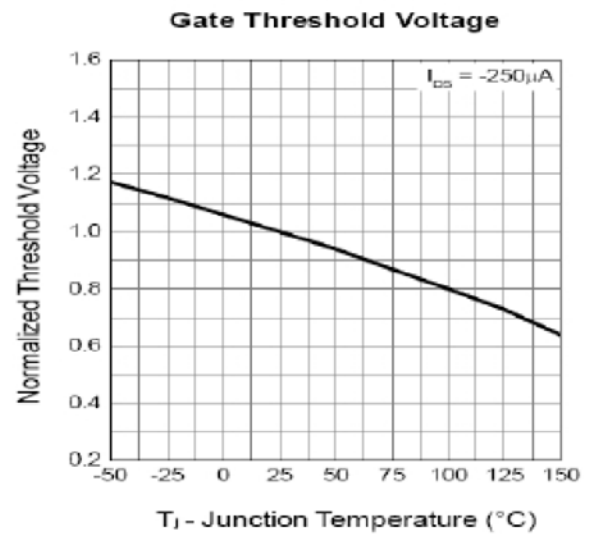
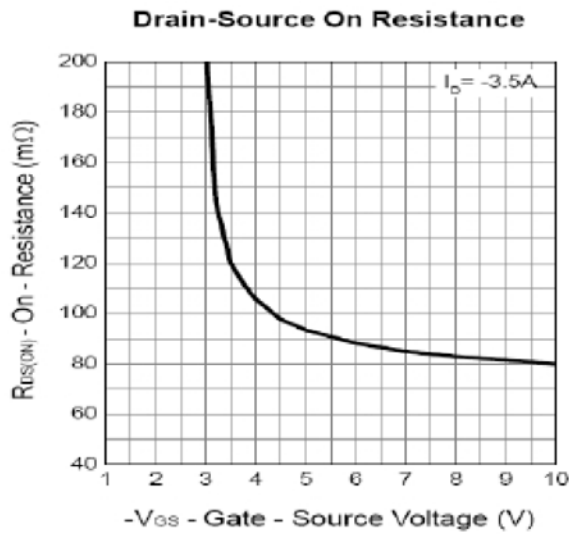
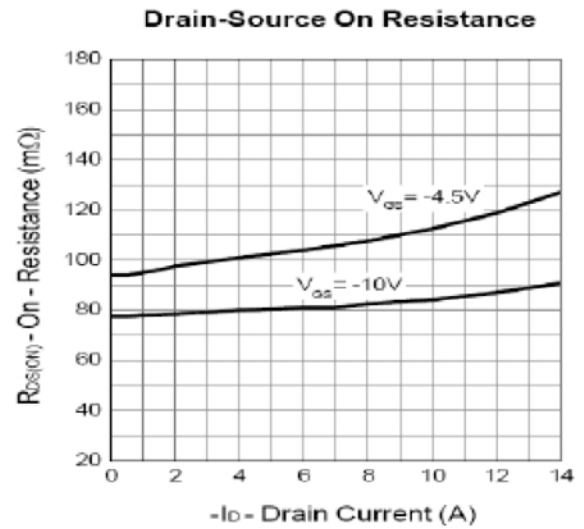
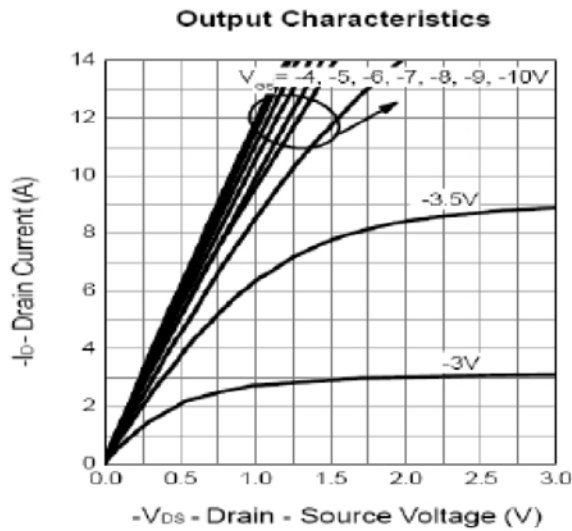


Thermal Transient Impedance



Typical Characteristics TA=25°C

P-Channel

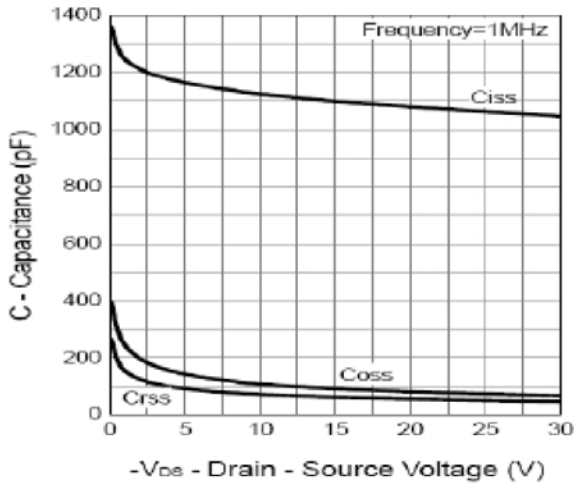




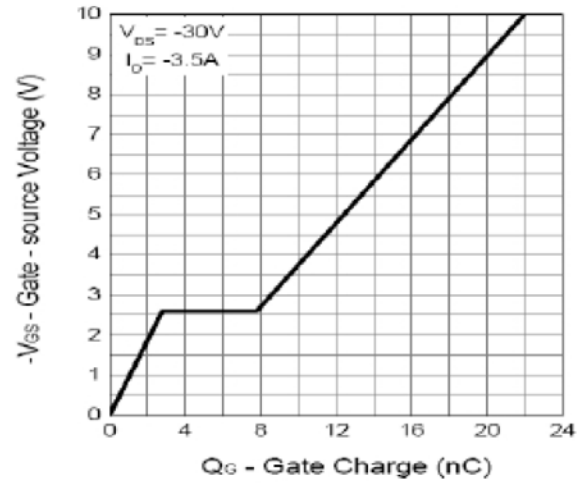
Typical Characteristics TA=25°C

P-Channel

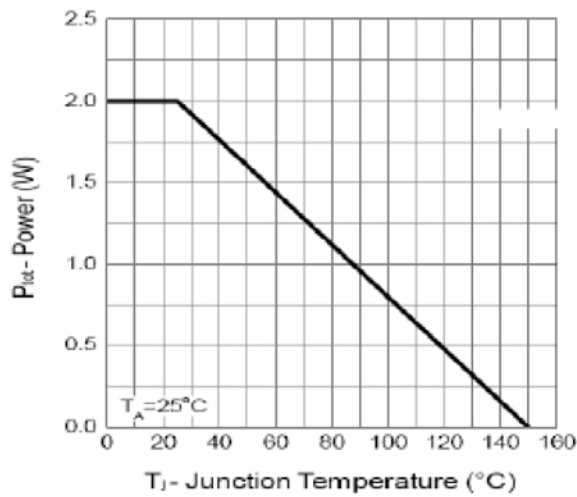
Capacitance



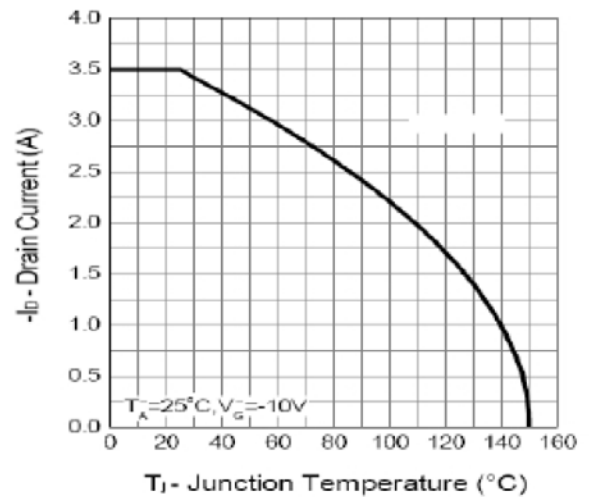
Gate Charge



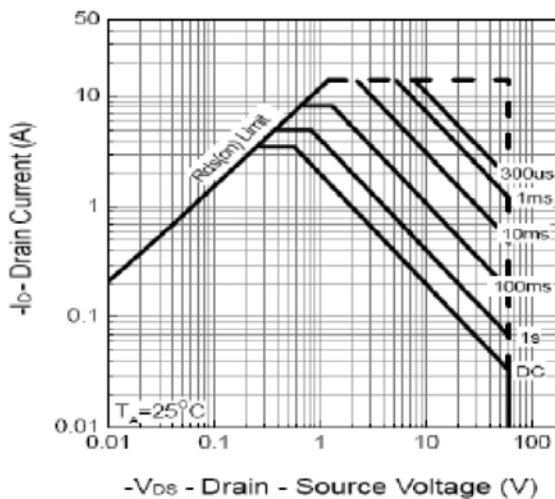
Power Dissipation



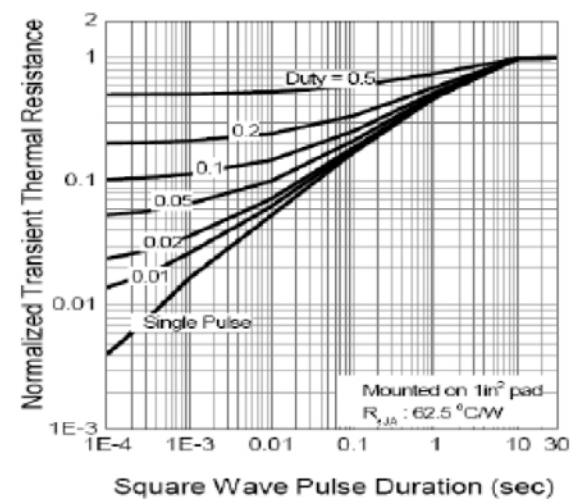
Drain Current



Safe Operation Area



Thermal Transient Impedance



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